

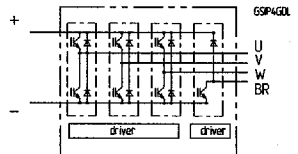
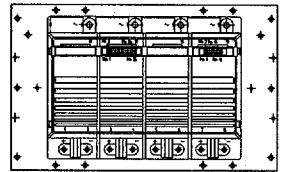
## SKiiP 312 GDL 120 - 404 WT (E/U)

Absolute Maximum Ratings		Values	Units
Symbol	Conditions <sup>1)</sup>		
IGBT & Inverse Diode			
V <sub>CES</sub>		1200	V
V <sub>CC</sub> <sup>10)</sup>	Operating DC link voltage	900	V
I <sub>C</sub>	T <sub>heatsink</sub> = 25 °C	300	A
I <sub>CM</sub>	T <sub>heatsink</sub> = 25 °C; t <sub>p</sub> < 1 ms	600	A
T <sub>J</sub> <sup>3)</sup>	IGBT & Diode	-55 ... +150	°C
V <sub>isot</sub> <sup>4)</sup>	AC, 1 min.	3000 <sup>5)</sup>	V
I <sub>F</sub>	T <sub>heatsink</sub> = 25 °C	240	A
I <sub>FM</sub>	T <sub>heatsink</sub> = 25 °C; t <sub>p</sub> < 1 ms	600	A
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin.; T <sub>J</sub> = 150 °C	2160	A
I <sub>t</sub> <sup>2)</sup> (Diode)	t <sub>p</sub> = 10 ms; T <sub>J</sub> = 150 °C	23,4	kA <sup>2</sup> s
Driver - inverter			
V <sub>S1</sub>	Stabilized power supply	18	V
V <sub>S2</sub> <sup>10)</sup>	Nonstabilized power supply	30	V
dv/dt	Primary to second. side	75	kV/μs
T <sub>op</sub> , T <sub>stg</sub>	Operating / stor. temperature	-25 ... +85	°C

Characteristics					
Symbol	Conditions <sup>1)</sup>	min.	typ.	max.	Units
V <sub>(BR)CES</sub>	Driver without power supply	≥ V <sub>CES</sub>	-	-	V
I <sub>CES</sub>	V <sub>GE</sub> = 0 } T <sub>J</sub> = 25 °C	-	0,3	-	mA
	V <sub>CE</sub> = V <sub>CES</sub> } T <sub>J</sub> = 125 °C	-	15	-	mA
V <sub>CEsat</sub> <sup>8)</sup>	I <sub>C</sub> = 225 A   T <sub>J</sub> = 25 (125) °C	-	2,75 (3,6)	-	V
V <sub>CEsat</sub> <sup>8)</sup>	I <sub>C</sub> = 300 A   T <sub>J</sub> = 25 (125) °C	-	3,15 (4,2)	-	V
I <sub>CETRIP</sub>	T <sub>J</sub> = 125 °C; V <sub>s</sub> = 15 V ± 0,6V	≥ 375	-	-	A
C <sub>CHC</sub>	per SKiiPACK AC side	-	0,8	-	nF
L <sub>CE</sub>	Top (Bottom)	-	15	-	nH
t <sub>d(on)</sub>	V <sub>CC</sub> = 600 V I <sub>C</sub> = 300 A T <sub>J</sub> = 125 °C inductive load	-	150	-	ns
t <sub>d(on)Driver</sub>		-	1,2	-	μs
t <sub>r</sub>		-	100	-	ns
t <sub>d(off)</sub>		-	0,7	-	μs
t <sub>d(off)Driver</sub>		-	1,2	-	μs
t <sub>f</sub>		-	80	-	ns
E <sub>on</sub> + E <sub>off</sub>		-	90	-	mJ
Inverse Diode <sup>2)</sup> - inverter					
V <sub>F</sub> <sup>8)</sup> = V <sub>EC</sub>	I <sub>F</sub> = 225 A   T <sub>J</sub> = 25 (125) °C	-	2,0(1,8)	-	V
	I <sub>F</sub> = 300 A   T <sub>J</sub> = 25 (125) °C	-	2,25(2,05)	-	V
V <sub>TO</sub>	T <sub>J</sub> = 125 °C	-	1,0	-	V
r <sub>T</sub>	T <sub>J</sub> = 125 °C	-	4,0	-	mΩ
E <sub>on</sub> + E <sub>off</sub>	I <sub>F</sub> = 300 A; T <sub>J</sub> = 125 °C	-	12	-	mJ
Diode <sup>2)</sup> - brake chopper (BC)					
V <sub>F</sub> <sup>8)</sup> = V <sub>EC</sub>	I <sub>F</sub> = 150 A   T <sub>J</sub> = 25 (125) °C	-	2,0(1,8)	-	V
	I <sub>F</sub> = 200 A   T <sub>J</sub> = 25 (125) °C	-	2,25(2,05)	-	V
V <sub>TO</sub>	T <sub>J</sub> = 125 °C	-	1,0	-	V
r <sub>T</sub>	T <sub>J</sub> = 125 °C	-	6,0	-	mΩ
Thermal Characteristics					
R <sub>thjh</sub>	per IGBT	-	0,08	-	K/W
R <sub>thjd</sub>	per diode inverter (BC)	-	0,27(0,4)	-	K/W
T <sub>tp</sub> <sup>11)</sup>	Over temperature protection	109	115	121	°C
R <sub>thha</sub> <sup>6)</sup>	P16/360 F; V <sub>air</sub> = 297 m <sup>3</sup> / h	-	0,036	-	K/W
Mechanical Data					
M <sub>dc</sub>	for DC terminals, SI Units	4	-	6	Nm
M <sub>ac</sub>	for AC terminals, SI Units	8	-	10	Nm
Case			S5		

## SKiiPACK® SK Integrated Intelligent Power PACK 3-phase bridge with brake chopper SKiiP 312 GDL 120 + Driver 404 WT (E/U)<sup>7)</sup>

Case S5

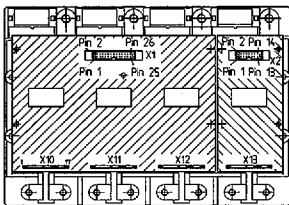


### Features

- Low thermal impedance
- Optimal thermal management with integrated heatsink
- Pressure contact technology with increased power cycling capability, compact design
- Low stray inductance
- High power, small losses
- Overtemp. protection
- Short circuit protection
- Isolated power supply

- 1) T<sub>heatsink</sub> = 25 °C, unless otherwise specified
- 2) CAL = Controlled Axial Lifetime Technology (soft and fast)
- 3) without driver
- 4) Driver input to DC link/AC output or DC link/AC output to heatsink
- 5) 3,5 kV (AC; on request)
- 6) other heatsink on request
- 7) W - Driver wire input  
T - Temperature protection  
E/U-voltage levels V<sub>DC</sub> br. chopper
- 8) Chip voltage drop
- 9) 24 V supply voltage selective
- 10) with SK-DC link (low inductance)
- 11) thermal reference for R<sub>thjh</sub>; R<sub>thha</sub>

**SKIIPACK®**  
**SK integrated**  
**Intelligent Power PACK**  
**3-phase bridge with**  
**brake chopper**  
**SKIIP 312 GDL 120**  
**+ Driver 404 WT (E/U)<sup>3)</sup>**



**SKIIP 312 GDL 120 - 404 WT (E/U)**  
**Driver for 3-phase bridge and brake chopper**

Absolute Maximum Ratings		3-phase bridge	brake chopper	Units	remark
Symbol	Conditions	Values			
V <sub>S1</sub>	supply voltage primary	18		V	
V <sub>S2</sub> <sup>1)</sup>	supply voltage primary	30		V	
I <sub>outmax</sub>	output peak current max.	± 10	± 1,5	A	
I <sub>outAV</sub>	output average current	± 50	± 90	A	
f <sub>swmax</sub>	switching frequency max.	12	5	kHz	
V <sub>CE</sub>	collector emitter voltage	1200		V	
dv/dt	sense across IGBT	75	50	kv/μs	
	rate of rise and fall of voltage (secondary to primary side)				
V <sub>isol IO</sub> <sup>4)</sup>	Isol. test volt. IN/OUT	2,5		kv~	
	(RMS; 1 min)				
V <sub>isol 12</sub>	Isol. test volt. OUT1 - OUT2	1,5		kv=	
T <sub>op</sub> , T <sub>stg</sub>	operating / stor. temperature	-25...+85		°C	

Characteristics		Values		Units	remark
Symbol	Conditions				
V <sub>S1</sub>	supply voltage primary	15,0 ± 4%		V	
V <sub>S2</sub> <sup>1)</sup>	supply voltage primary	24,0		V	+25%/-15%
V <sub>uvs</sub>	supply undervolt. monitoring	13		V	
V <sub>uvs</sub> <sup>1)</sup>	supply undervolt. monitoring	19,5	16	V	
I <sub>S01</sub>	sup. current pr.side (standby)	380	67	mA	
I <sub>S02</sub> <sup>1)</sup>	sup. current pr.side (standby)	300	67	mA	
I <sub>S1</sub>	sup. current pr.side (max)	900	77	mA	
I <sub>S2</sub> <sup>1)</sup>	sup. current pr.side (max)	700	77	mA	
V <sub>IT+</sub>	input thresh. volt. (high) min	12,9		V	
V <sub>IT-</sub>	input thresh. volt. (low) max.	2,1		V	
V <sub>GE(on)</sub>	turn-on output gate voltage	15	15	V	
V <sub>GE(off)</sub>	turn-off output gate voltage	- 8	0	V	
t <sub>d(on)</sub>	propagation delay time on	1,2	< 20	μs	typ.
t <sub>d(off)</sub>	propagation delay time off	1,2	< 25	μs	typ.
t <sub>TD</sub>	dead time of interlock	3		μs	typ.
V <sub>CEstat</sub>	V <sub>CE</sub> -thresh. st. monitoring	5,1	5	V	typ.
V <sub>CEdyn</sub>	V <sub>CE</sub> -thresh. dyn. monitoring	9,5	10	V	typ.
V <sub>ol</sub> <sup>2)</sup>	logic low output voltage	< 0,5		V	15mA sink
			< 0,6	V	2,5mA sink
V <sub>OH</sub> <sup>2)</sup>	logic high output voltage	max.30		V	
V <sub>RESET L</sub>	Input voltage RESET Low	< 2		V	
V <sub>RESET H</sub>	Input voltage RESET High	> 12		V	
V <sub>IL</sub>	logic low input volt. Chop. ext. ON	< 5		V	> 5 mA
V <sub>IH</sub>	logic high input volt. Chop.ext. ON	> 11,5		V	< 1 mA
t <sub>pdon-error</sub>	propag. delay time-on error	6	< 60	μs	
t <sub>p RESET</sub>	min. pulse width error	5		μs	
	memory RESET		300	ms	
T <sub>err</sub>	max. temperature	115 ± 6		°C	
I <sub>AQmax</sub>	max. output current	± 5		mA	pin 20

Voltage levels V <sub>DC</sub> brake <sup>5)</sup>		Values		Units	remark
Symbol	Conditions				
V <sub>DCmax</sub>	DC-link voltage (max)		730	V	E
			860	V	U
V <sub>DCON</sub>	Chopper voltage ON		681	V	E
			802	V	U
V <sub>DCOFF</sub>	Chopper voltage OFF		667	V	E
			786	V	U

**Features**

**3-phase bridge**

- CMOS compatible inputs
- Short circuit protection by V<sub>CE</sub> monitoring and soft switch off
- Drive interlock top/bottom
- Isolation by transformers
- Supply undervoltage protection
- Overtemperature protection

**Features**

**brake chopper**

- Short circuit protection by V<sub>CE</sub> monitoring and soft switch off
- Self controlled switching
- Supply undervoltage protection
- Overtemperature protection

1) 24 V - supply voltage selective

2) Open collector output external pull-up resistor necessary

3) W - Driver wire input  
 T - Temperature protection

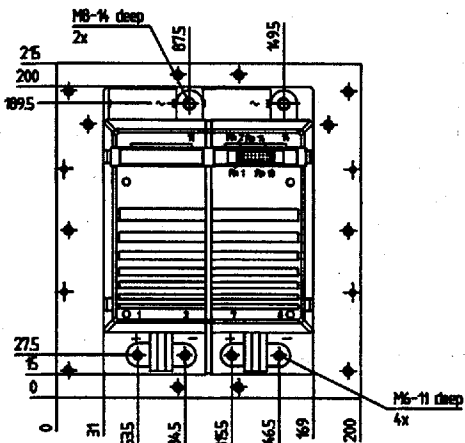
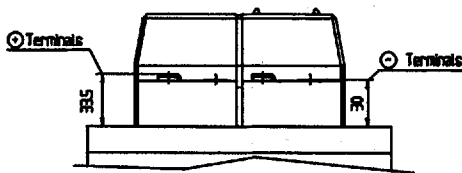
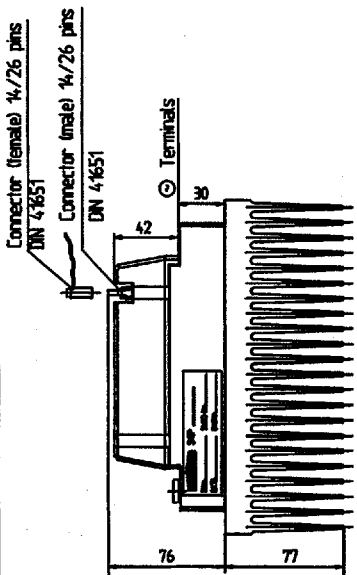
E/U-voltage levels V<sub>DC</sub> br. chopper  
 E - EUROPE (400 V<sub>RMS</sub>)  
 U - USA (460 V<sub>RMS</sub>)

4) 3,5 kV<sub>AC</sub> (on request)

5) other levels (on request)

**Case S2  
SKIIPACK  
View from right**

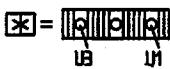
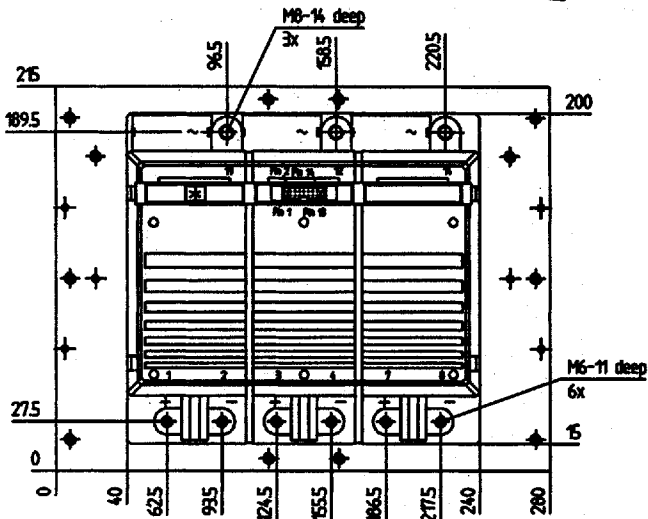
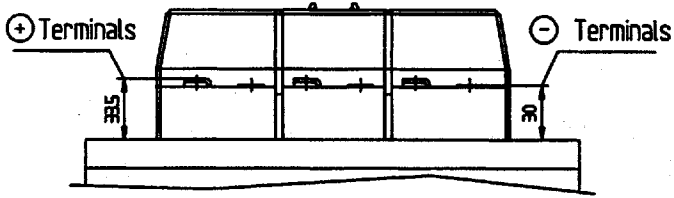
**SKIIPACK 2 - GB**



Case S3

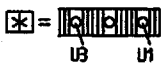
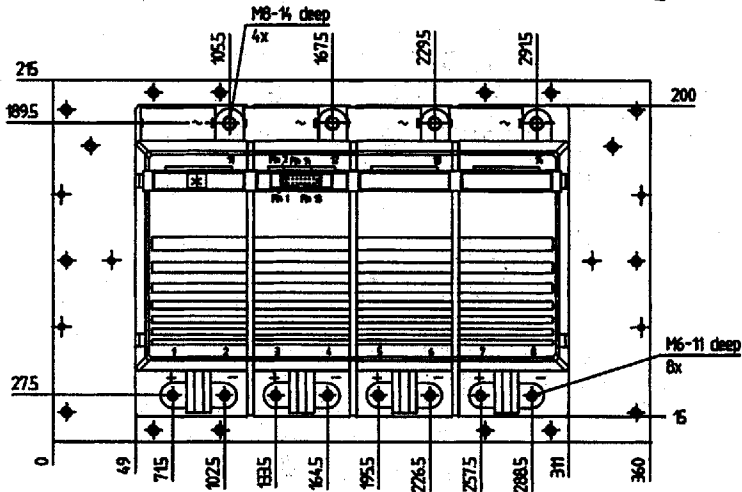
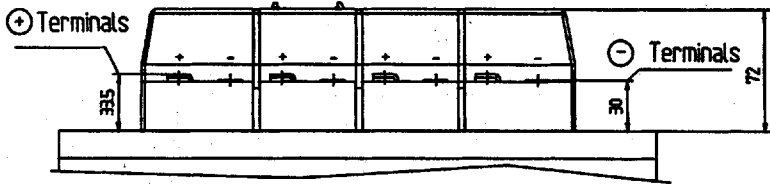
SKIIPACK 3 - GB, GD

CASES3

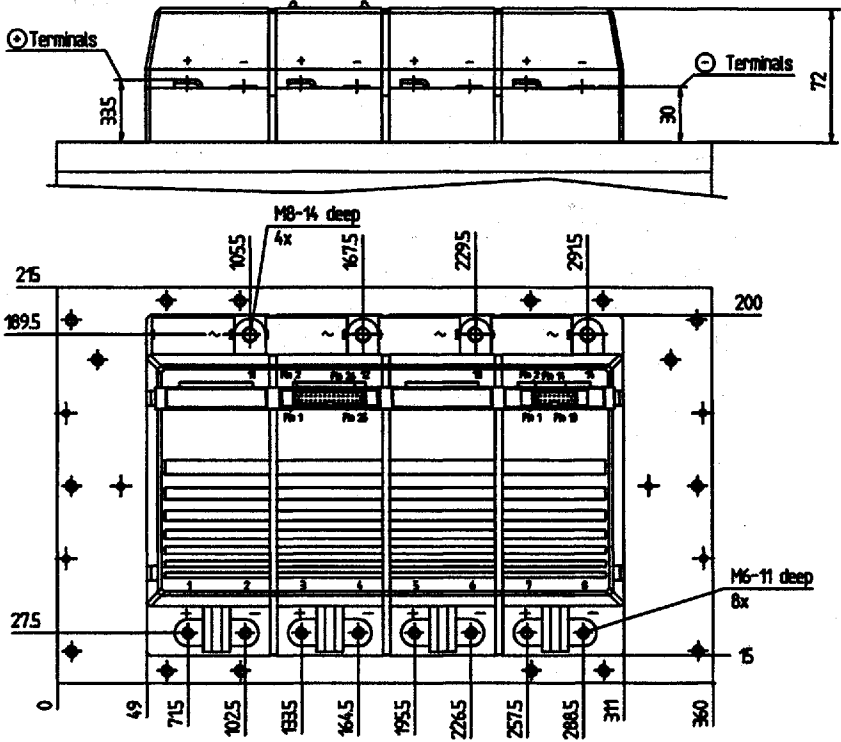


Version SKiIP ... GB ... FT (Fibreoptic input)

CASES4



Version SKiIP ... GB ... FT (Fibreoptic input)



**SKIIPACK view from right**

